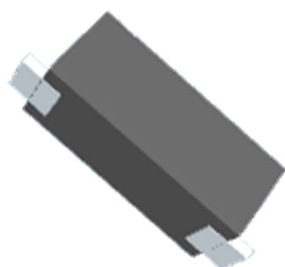


# SMF (SOD-123)

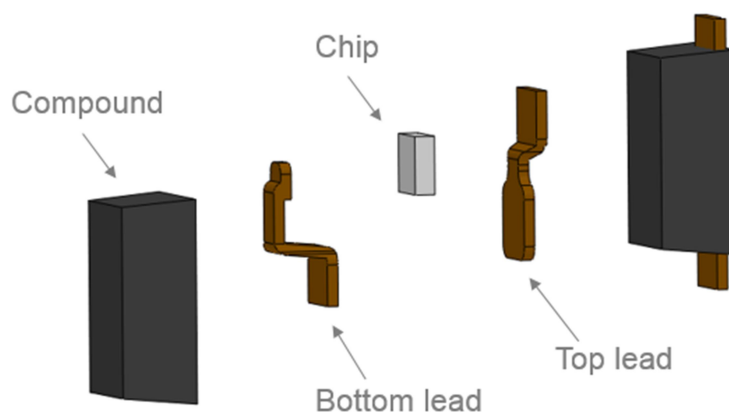
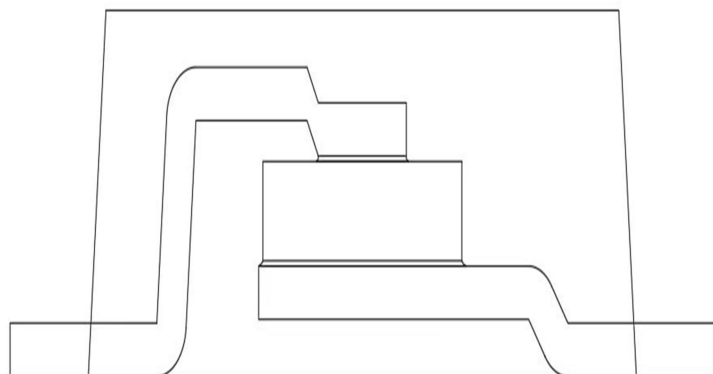


SMF

## 1: Certification

- System:
  - IATF 16949
  - ISO9001
  - ISO14001
  - ISO45001
- ROHS/REACH/ELV:
  - Lead frame、Solder、Molding compound、Post plating.
- UL 94: V-0
- MSL : level 1
- Whisker Test: JESD 201 class 2
- Solder bath temperature : 260°C maximum, 10 s

## 2: Internal Structure Diagram



### Meet Die Size

	Lead Pad(mm)	Die size(mil)	Wafer thickness (um)
Max	0.55	50.00	300.00
Min	0.35	32.00	150.00

## 3: Production line advantage

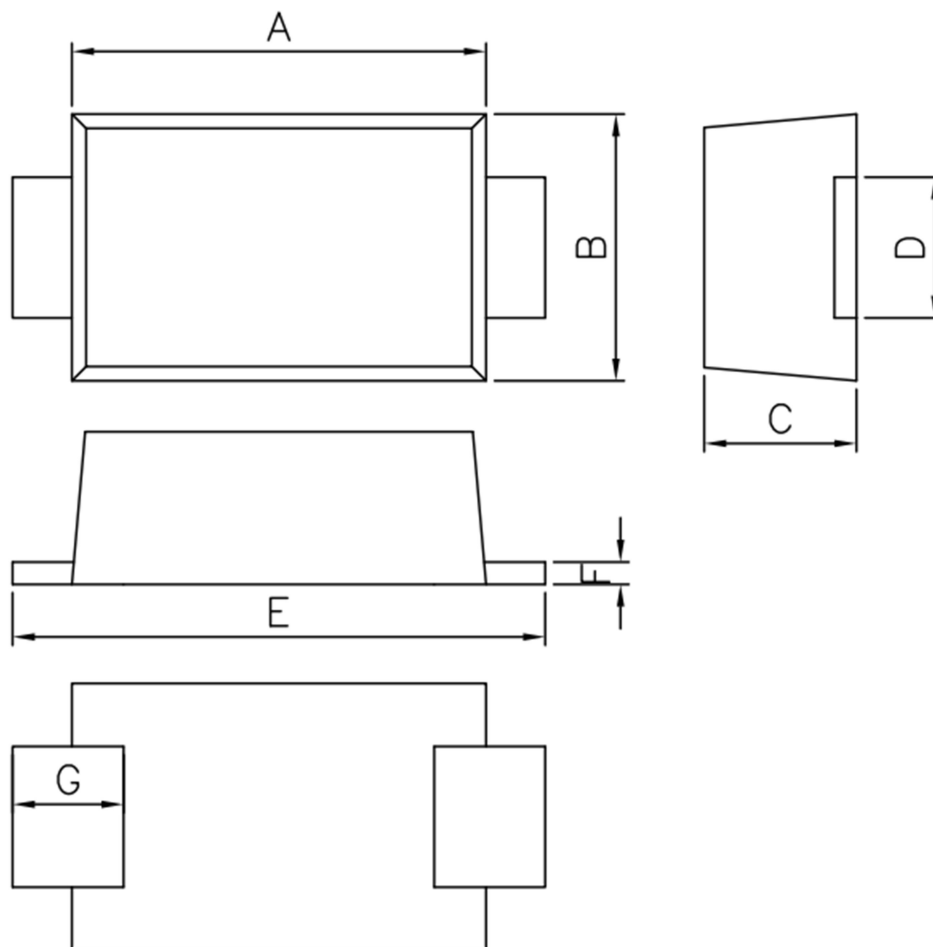
- 100% AOI in TMTT.
- Automated production line for all process.

## 4: Reliability Experiment

Test	Test Condition
HAST	80%VR/130°C/85%R.H.
Temp. Cycling	1000 cycles form -55°to 150°C
UHAIST	96 hours at Ta = 130°C, RH = 85%
HTRB	1000 hours 150°
RSH	260°C , 10 s

## 5: Package Outline Dimensions in millimeters

### 5.1 POD



SYMBOL	MILLIMETERS		
	Normal	MIN	MAX
A	2.80	2.75	2.85
B	1.80	1.75	1.85
C	1.03	1.00	1.06
D	0.95	0.90	1.00
E	3.60	3.50	3.70
F	0.15	0.13	0.17
G	0.75		